

PRODUCT BULLETIN

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Axon Circuit Introduces New Final Finish Fabrication Capabilities

In today's competitive marketplace, it is imperative to offer quick turn-key solutions and products/services. We at Axon Circuit value your commitment to your customers; therefore, we have expanded our fabrication capabilities and are now offering **1-day to 3-day delivery*** on single-sided, double-sided and multi-layer PCBs that require additional surface plating, including electroless nickel, immersion gold/silver, and Entek Plus 106A OSP. Please refer to the chart below for specifications.

***NOTE:** Extra charges may apply depending on delivery requirements. For additional information, please contact the Axon Circuit Sales Team at **1-800-226-2966**.

Finish	Class1	Class2	Class3
Gold (min.) for edge-board Connectors and areas not to be soldered	0.8µm	0.8µm	1.3µm
Gold (max) on areas to be soldered	0.8µm	0.8µm	0.8µm
Gold (min) on areas to be wire bonded (ultrasonic)	0.05µm	0.05µm	0.16µm
Gold (min) on areas to be wire bonded (thermosonic)	0.03µm	0.03µm	0.6µm
Nickel (min) for edge-board connectors	2.0µm	2.5µm	2.5µm
Nickel (min) barrier to prevent formation of copper-tin compounds**	1.0µm	1.3µm	1.3µm
Electroless Nickel	2.5µm – 5.0µm	2.5µm – 5.0µm	2.5µm – 5.0µm
Immersion Gold	0.08µm – 0.23µm	0.08µm – 0.23µm	0.08µm – 0.23µm
Solder coat over bare copper	Coverage and solderable	Coverage and solderable	Coverage and solderable
Organic solderability preservative	Solderable	Solderable	Solderable
Bare Copper	None	None	None
Surface and Holes			
Copper* (Avg. min)	20µm	20µm	25µm
Min. thin areas***	18µm	18µm	20µm
Blind Vias			
Copper* (Avg. min)	20µm	20µm	25µm
Min. thin areas***	18µm	18µm	20µm
Buried Vias			
Copper* (Avg. min)	13µm	15µm	15µm
Min. thin areas***	11µm	13µm	13µm

* Copper-plating thickness applies to surface and hole walls.

** Nickel platings used under tin-lead or solder coating for high temperature operating environments act as a barrier to prevent the formation of copper-tin compounds.

*** For Class 3 boards having a drilled hole diameter <0.35mm and having an aspect ratio >3.5:1, the minimum thin area copper plating in the hole shall be 25µm